



ProLight PM2B-1LWE PM2B-1LxE-Rx 1W High CRI Power LED Technical Datasheet Version: 2.2

### Features

- Good color uniformity
- Industry best moisture sensitivity level JEDEC Level 1
- Lead free reflow soldering
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV
- Superior ESD protection

### **Typical Applications**

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

#### **Emitter Mechanical Dimensions**



Notes:

- 1. The Anode side of the device is denoted by a hole in the lead frame.
- 2. Electrical insulation between the case and the board is required. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. Unless otherwise indicated, tolerances are  $\pm$  0.20mm.
- 6. Please do not bend the leads of the LED, otherwise it will damage the LED.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

\*The appearance and specifications of the product may be modified for improvement without notice.

Radiation	Color	Part Number	Lumious Flu	CRI	
Pattern	COIDI	Emitter	Minimum	Typical	Typical
	White	PM2B-1LWE PM2B-1I VF-R7	110 87.4	152	74
Lambertian	Warm White White	PM2B-1LVE-R7 PM2B-1LWE-R8	87.4 100	125 130	77 84
	Warm White	PM2B-1LVE-R8	87.4	122	80

# Flux Characteristics at 350mA, $T_J = 25^{\circ}C$

• ProLight maintains a tolerance of ± 10% on flux and power measurements.

• Please do not drive at rated current more than 1 second without proper heat sink.

# Electrical Characteristics at 350mA, $T_J = 25^{\circ}C$

Color	Forward Voltage V <sub>F</sub> (V)			Thermal Resistance
Color	Min.	Тур.	Max.	Junction to Slug (°C/ W)
White	2.85	3.3	3.85	10
Warm White	2.85	3.3	3.85	10

• ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

# Optical Characteristics at 350mA, $T_J = 25^{\circ}C$

				Total included Angle	Viewing Angle
Color	Co	lor Temperature C	CCT	(degrees)	(degrees)
	Min.	Typ.	Max.	θ <sub>0.90V</sub>	2 θ <sub>1/2</sub>
White	4100 K	5500 K	10000 K	180	130
Warm White	2700 K	3300 K	4100 K	180	130

• ProLight maintains a tolerance of ± 5% for CCT measurements.

# **Absolute Maximum Ratings**

Parameter	White/Warm White
DC Forward Current (mA)	350
Peak Pulsed Forward Current (mA)	500 (less than 1/10 duty cycle@1KHz)
Average Forward Current (mA)	350
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	±4000V (Class III)
LED Junction Temperature	120°C
Operating Board Temperature at Maximum DC Forward Current	-40°C - 105°C
Storage Temperature	-40°C - 120°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias

# Forward Voltage Bin Structure

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
	А	2.85	3.10
\//bito	В	3.10	3.35
White	D	3.35	3.60
	E	3.60	3.85
	А	2.85	3.10
Warm White	В	3.10	3.35
warm white	D	3.35	3.60
	E	3.60	3.85

• ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Part Number	Bin Code	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)	Available Color Bins
	V1	110	120	[1]
	V2	120	130	All
PM2B-1LWE	W1	130	140	All
	W2	140	155	All
	X1	155	170	Xx,Wx,Vx <sup>[1]</sup>
	U1	87.4	100	【1】
	U2	100	110	All
PM2B-1LVE-R7	V1	110	120	All
	V2	120	130	All
	W1	130	140	[1]
	U2	100	110	All
	V1	110	120	All
PM2B-1LWE-R8	V2	120	130	All
	W1	130	140	Xx,Wx,Vx <sup>[1]</sup>
	U1	87.4	100	【1】
	U2	100	110	All
PM2B-1LVE-R8	V1	110	120	All
	V2	120	130	All
	W1	130	140	[1]

## **Photometric Luminous Flux Bin Structure**

• ProLight maintains a tolerance of ± 10% on flux and power measurements.

 ${\ensuremath{\bullet}}$  The flux bin of the product may be modified for improvement without notice.

• <sup>[1]</sup> The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.



White and Warm White Binning Structure Graphical Representation



# **Color Bins**

#### White Bin Structure

Bin Code	х	У	Typ. CCT (K)	Bin Code	x	у	Typ. CCT (K)	
	0.378	0.382			0.329	0.345		
то	0.374	0.366	4300	WN	0.316	0.333	5970	
10	0.360	0.357	4000	VVIN	0.315	0.344	0070	
	0.362	0.372			0.329	0.357		
	0.382	0.397			0.329	0.331		
TN	0.378	0.382	4300	WP	0.329	0.320	5970	
	0.362	0.372	4000	VVI	0.318	0.310	5570	
	0.365	0.386			0.317	0.320		
	0.362	0.372			0.308	0.311		
U0	0.360	0.357	4750	X0	0.305	0.322	6650	
00	0.344	0.344	4750	4700	70	0.316	0.333	0000
	0.346	0.359			0.317	0.320		
	0.365	0.386			0.305	0.322		
UN	0.362	0.372	4750	XN	0.303	0.333	6650	
ON	0.346	0.359	4750		0.315	0.344	0000	
	0.347	0.372			0.316	0.333		
	0.329	0.331			0.308	0.311		
V0	0.329	0.345	5320	XP	0.317	0.320	6650	
vo	0.346	0.359	5520		0.319	0.300		
	0.344	0.344			0.311	0.293		
	0.329	0.345			0.308	0.311		
VN	0.329	0.357	5320	Y0	0.283	0.284	8000	
VIN	0.347	0.372	5520	10	0.274	0.301	0000	
	0.346	0.359			0.303	0.333		
	0.329	0.345			0.308	0.311		
W0	0.329	0.331	5970	YA	0.311	0.293	8000	
000	0.317	0.320	5910		0.290	0.270	0000	
	0.316	0.333			0.283	0.284		

 $\bullet$  Tolerance on each color bin (x , y) is  $\pm \ 0.01$ 

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

# **Color Bins**

#### Warm White Bin Structure

Bin Code	x	У	Typ. CCT (K)	Bin Code	x	У	Typ. CCT (K)
	0.453	0.416			0.409	0.400	
MO	0.444	0.399	2770	Q0	0.402	0.382	3370
IVIO	0.459	0.403	2110	QU	0.416	0.389	3370
	0.467	0.419			0.424	0.407	
	0.460	0.430			0.414	0.414	
M1	0.453	0.416	2770	Q1	0.409	0.400	3370
	0.467	0.419	2110	QI	0.424	0.407	3370
	0.473	0.432			0.430	0.421	
	0.438	0.412			0.392	0.391	
N0	0.429	0.394	2950	R0	0.387	0.374	3650
NU	0.444	0.399	2950	RU	0.402	0.382	3050
	0.453 0.416		0.409	0.400			
	0.444	0.426			0.414	0.414	
N1	0.438	0.412	2950	R1	0.409	0.400	3650
	0.453	0.416	2950	N1	0.392	0.391	3050
	0.460	0.430	0.430 0.3	0.397	0.406		
	0.424	0.407			0.392	0.391	
P0	0.416	0.389	3150	S0	0.387	0.374	3950
10	0.429	0.394	5150	50	0.374	0.366	3930
	0.438	0.412			0.378	0.382	
	0.430	0.421			0.397	0.406	
P1	0.424	0.407	3150	S1	0.392	0.391	3950
ΓI	0.438	0.412	3150	31	0.378	0.382	3950
	0.444	0.426			0.382	0.397	

• Tolerance on each color bin (x , y) is  $\pm 0.01$ 

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color Spectrum,  $T_J = 25^{\circ}C$ 

1. White



#### 2. Warm White For R7







## **Light Output Characteristics**



#### Relative Light Output vs. Junction Temperature at 350mA





Voltage for White, Warm White.

Fig 2. Relative Luminous Flux vs. Forward Current for White, Warm White at  $T_J$ =25 $^\circ\!C$  maintained.

### **Ambient Temperature vs. Maximum Forward Current**



1. White, Warm White ( $T_{JMAX} = 120^{\circ}C$ )

## **Typical Representative Spatial Radiation Pattern**

Lambertian Radiation Pattern



# Moisture Sensitivity Level - JEDEC Level 1

			Soak Requirements				
Level	Floor Life		Standard		Accelerated Environment		
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions	
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA	
i Uniimitea	85% RH	100 +5/-0	85% RH	IN/A	NA		

• The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.

				Soak Req	uirements	
Level	Floor	r Life	Stan	dard	Accelerated	Environment
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA
I	Onininited	85% RH	100 +5/-0	85% RH	NA NA	NA NA
2	1 voor	≤30°C /	168 +5/-0	85°C /	NA	NA
2	1 year	60% RH	100 +5/-0	60% RH	INA	NA
2a	4 weeks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /
Za	4 weeks	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH
3	168 hours	≤30°C /	192 +5/-0	30°C /	40 +1/-0	60°C /
5	100 110015	60% RH	192 +5/-0	60% RH	40 + 17-0	60% RH
4	72 hours	≤30°C /	96 +2/-0	30°C /	20 +0.5/-0	60°C /
t	72 110015	60% RH	90 +2/-0	60% RH	20 +0.5/-0	60% RH
5	48 hours	≤30°C /	72 +2/-0	30°C /	15 +0.5/-0	60°C /
5	40 110013	60% RH	12 +2/-0	60% RH	10 +0.5/-0	60% RH
5a	24 hours	≤30°C /	48 +2/-0	30°C /	10 +0.5/-0	60°C /
Ja	24 110015	60% RH	40 +2/-0	60% RH	10 +0.5/-0	60% RH
6	Time on Label	≤30°C /	Time on Label	30°C /	NA	NA
0	(TOL)	60% RH	(TOL)	60% RH		NA NA

• Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

# **Qualification Reliability Testing**

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I <sub>F</sub> = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I <sub>F</sub> = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Non-operating Thermal Shock (TMSK)	-40°C to 120°C, 20 min. dwell, <20 sec. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

1. Depending on the maximum derating curve.

2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement		
nem		Min.	Max.	
Forward Voltage (V <sub>F</sub> )	I <sub>F</sub> = max DC		Initial Level x 1.1	
Luminous Flux or Radiometric Power ( $\Phi_V$ )	I <sub>F</sub> = max DC	Initial Level x 0.7		
Reverse Current (I <sub>R</sub> )	V <sub>R</sub> = 5V		50 µA	

\* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

# **Recommended Solder Pad Design**



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

### **Reflow Soldering Condition**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate $(T_{Smax}$ to $T_{P})$	3°C / second max.	3°C / second max.
Preheat		
– Temperature Min (T <sub>Smin</sub> )	100°C	150°C
<ul> <li>Temperature Max (T<sub>Smax</sub>)</li> </ul>	150°C	200°C
– Time ( $t_{Smin}$ to $t_{Smax}$ )	60-120 seconds	60-180 seconds
Time maintained above:		
– Temperature (T <sub>L</sub> )	183°C	217°C
– Time (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak/Classification Temperature $(T_P)$	240°C	260°C
Time Within 5°C of Actual Peak Temperature $(t_P)$	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a
  double-head soldering iron should be used. It should be confirmed beforehand whether the
  characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

### **Emitter Tube Packaging**



#### Notes:

- 1. 50 pieces per tube.
- 2. Drawing not to scale.
- 3. All dimensions are in millimeters.
- 4. All dimendions without tolerances are for reference only.
- \*\*Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

### **Precaution for Use**

- Storage
- Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB. • The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. <u>http://www.prolightopto.com/</u>